

LPC5514JEV59

Active

Fully qualified to meet NXP quality and reliability requirements. Available for production quantity orders.

Package

VFBGA59

VFBGA59, very thin fine-pitch ball grid array package, 59 terminals, 0.4 mm pitch, 4 mm x 4 mm x 0.77 mm body.



Buy Options

Operating Features

Environmental

Quality

Shipping

Buy Options

LPC5514JEV59E

12NC: 935434229551

Active

Packing: TRAY-Tray, Bakeable, Single in Drypack

Min. Package Quantity: 490 Min. Order Quantity: 490

Lead Time: 13

> Available Distributors: LPC5514JEV59E

LPC5514JEV59Y

12NC: 935434229518

Active

Packing: REEL-Reel 13" Q1/T1 in Drypack

Min. Package Quantity: 3000 Min. Order Quantity: 3000

Lead Time: 13

> Available Distributors: LPC5514JEV59Y

Operating Features

No information available

Environmental

Part/12NC	PbFree	EU RoHS	Halogen Free	RHF Indicator	REACH SVHC	Weight (mg)
LPC5514JEV59E (935434229551)	Yes	Yes Certificate Of Analysis (CoA)	Yes	D	REACH SVHC	32.84414874240668
LPC5514JEV59Y (935434229518)	Yes	Yes Certificate Of Analysis (CoA)	Yes	D	REACH SVHC	32.84414874240668

Quality

Part/12NC	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	
		Lead Free Soldering	Lead Soldering	Lead Free Soldering
LPC5514JEV59E (935434229551)	No	3	240	260
LPC5514JEV59Y (935434229518)	No	3	240	260

Shipping

Part/12NC	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)
LPC5514JEV59E (935434229551)	854231	3A991A2
LPC5514JEV59Y (935434229518)	854231	3A991A2





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